



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

3. DATE-CODE LOCATION. AND DATE-CODE *YMDLS*
 IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)

4. LGA1366 TO BE INDICATED IN THIS AREA.

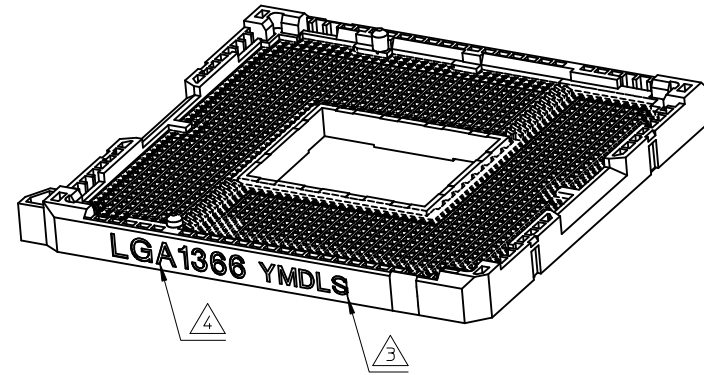
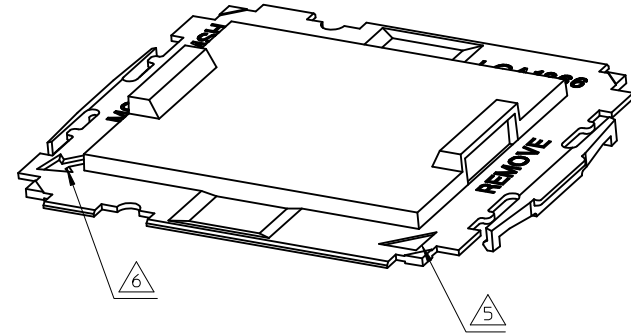
5. SOCKET PIN 1 INDICATOR.

6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

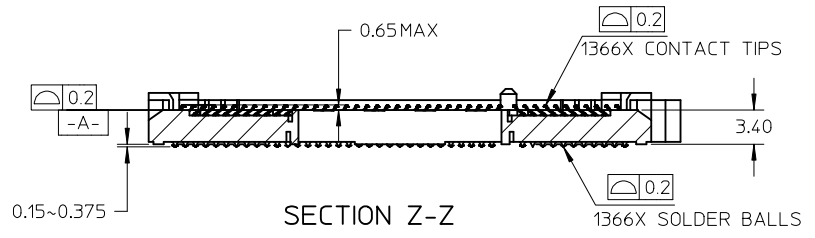
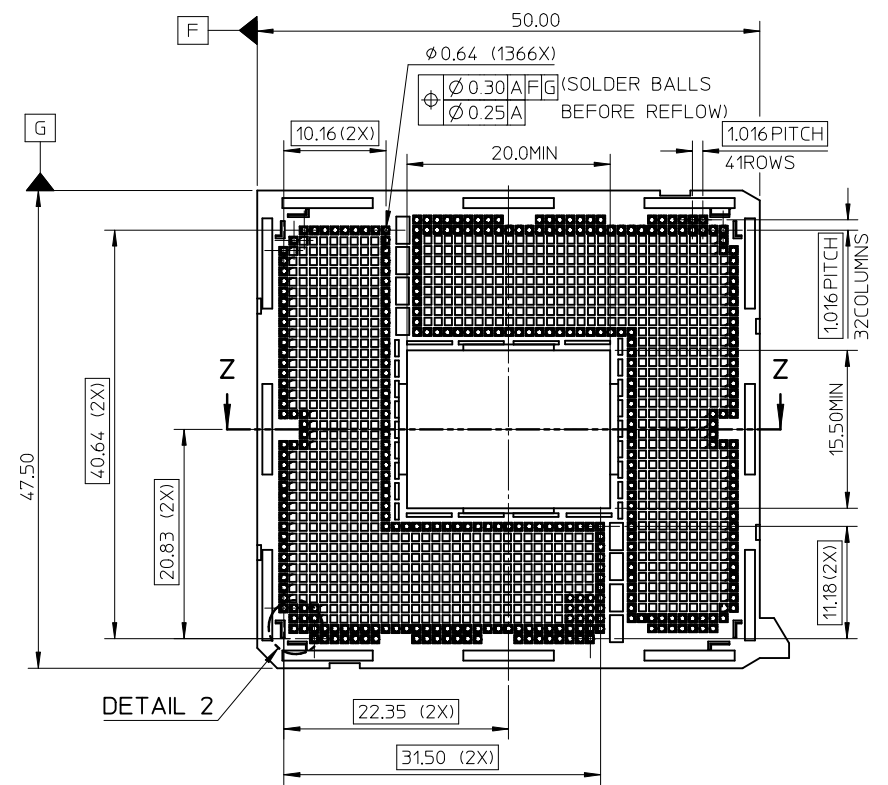
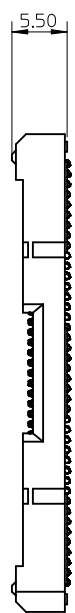
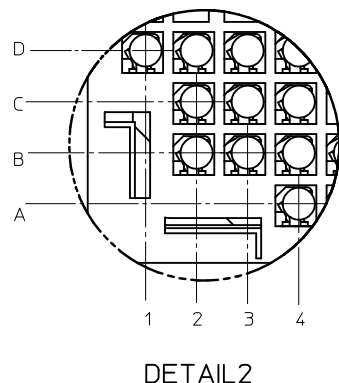
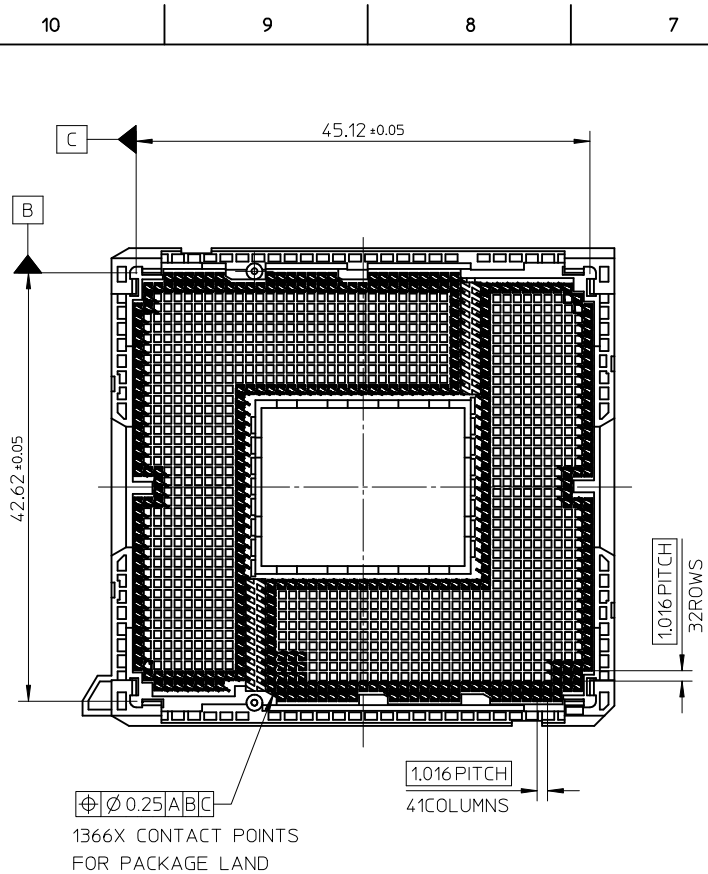
8. PRODUCT PACKAGE PK-47594-003 APPLIES.

9. THE PARTS 475940001/0002 COMPLIANT TO RoHS
 DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.



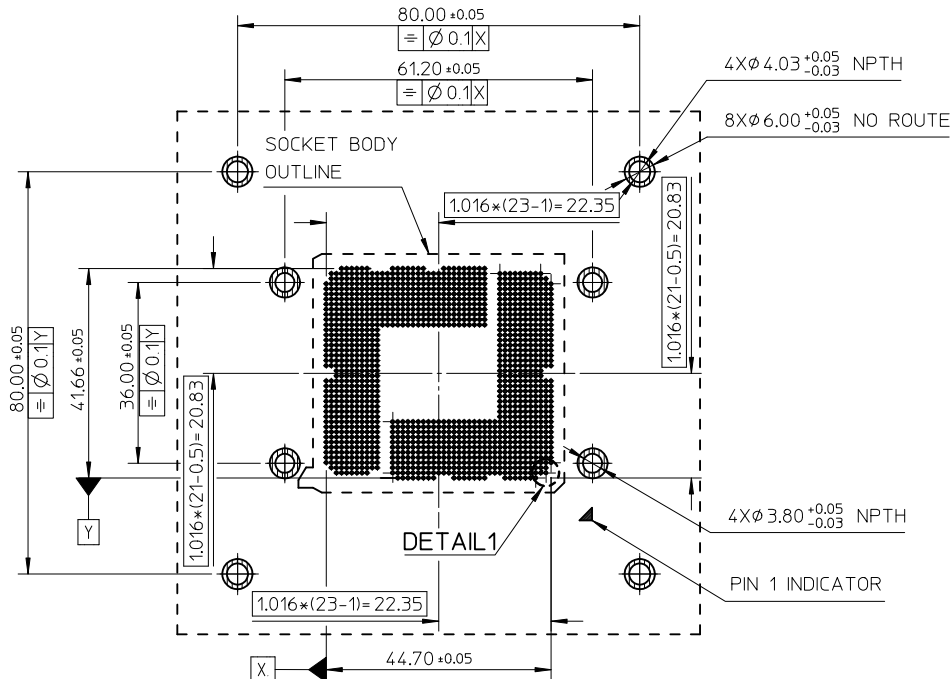
LGA1366 SOCKET PART NUMBER LIST				
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT
475940002	GENERAL	30u*(0.76um)	LEAD FREE	YES
475940001	GENERAL	15u*(0.38um)		

ENTER DESCRIPTION EC NO: SH2012-0177 DRWN: ZHANG11 CHKD: APPR: AYIN 2011/12/07 2011/12/14	DESCRIPTION REV 2011/12/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		$F_A=0$ $F_B=0$ $F_C=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 1°	MM ONLY	2:1	METRIC	
			DRAWN BY: WFDENG DATE: 2008/09/16 CHECKED BY: JKACHLIC DATE: 2008/09/16 APPROVED BY: AYIN DATE: 2010/10/22	TITLE	LGA1366 SOCKET FULL ASSEMBLY		
		MATERIAL NO. SEE TABLE DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MOLEX INCORPORATED DOCUMENT NO. SD-47594-001 SHEET NO. 1 OF 3				

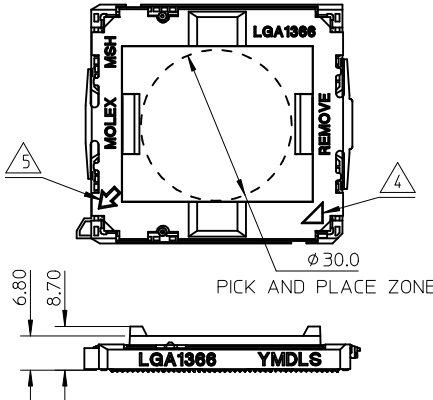


ENTER DESCRIPTION EC NO: SH2012-0177 DRWN: ZHANG11 CHKD: APPR: AYIN	REV 2011/12/14	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
			$\nabla = 0$	mm	INCH	MM ONLY		2:1	METRIC			
			$\nabla = 0$	4 PLACES ± ---	± ---	DRAWN BY	DATE	TITLE				
			$\nabla = 0$	3 PLACES ± ---	± ---	WFDENG	2008/09/16	LGA1366 SOCKET FULL ASSEMBLY				
			2 PLACES ± 0.20	± ---	CHECKED BY	DATE	MOLEX INCORPORATED					
			1 PLACE ± 0.25	± ---	JKACHLIC	2008/09/16	SD-47594-001					
			ANGULAR ± 1°			APPROVED BY	DATE	DOCUMENT NO.			SHEET NO.	
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		AYIN	2010/10/22	SEE TABLE			2 OF 3	
						MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
						SIZE						
						A3						

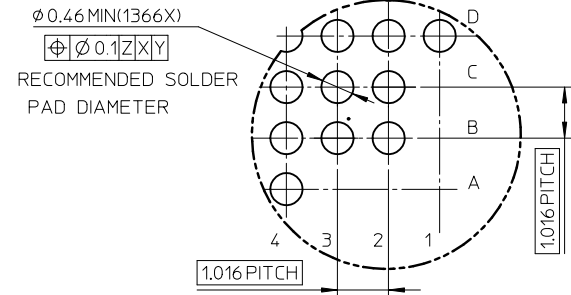
10 9 8 7 6 5 4 3 2 1



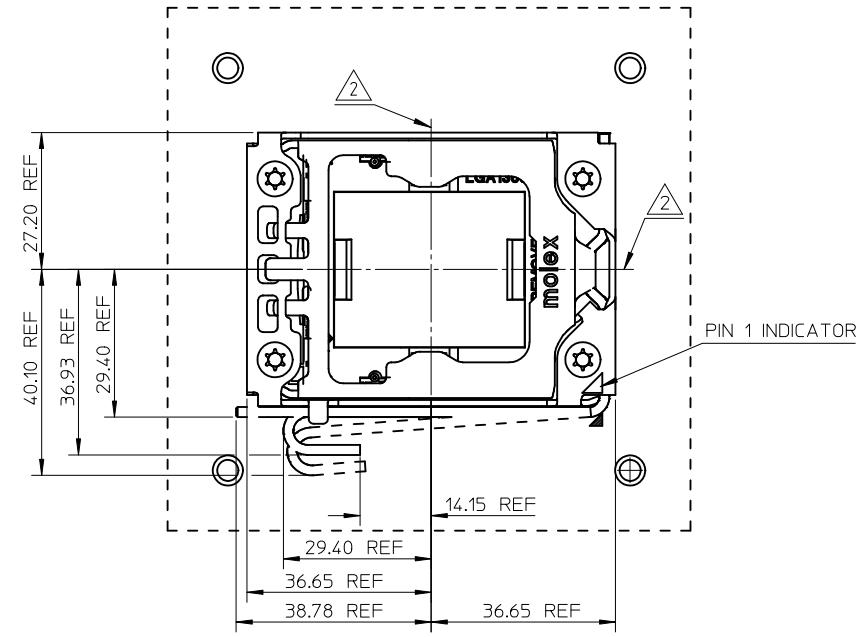
RECOMMEND PCB LAYOUT THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
1. DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
 2. GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
 3. BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 4. SOCKET PIN 1 INDICATOR.
 5. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
 6. ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.



DETAIL1 SCALE 10:1



SOCKET ON PCB(FOR REFERENCE ONLY) LOAD PLATE IS NOT LOCKED

ENTER DESCRIPTION EC NO: SH2012-0177 DRWN: ZHANG11 CHKD: APPR: AYIN 2011/12/07 2011/12/14	QUALITY SYMBOLS F=0 F=0 F=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± ---	mm INCH	DRAWN BY: WFDENG CHECKED BY: JKACHLIC APPROVED BY: AYIN MATERIAL NO.	DATE: 2008/09/16 DATE: 2008/09/16 DATE: 2010/10/22	TITLE: LGA1366 SOCKET FULL ASSEMBLY	MOLEX INCORPORATED	SHEET NO. 3 OF 3
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	DOCUMENT NO. SD-47594-001	MOLEX INCORPORATED		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

9 8 7 6 5 4 3 2 1

NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

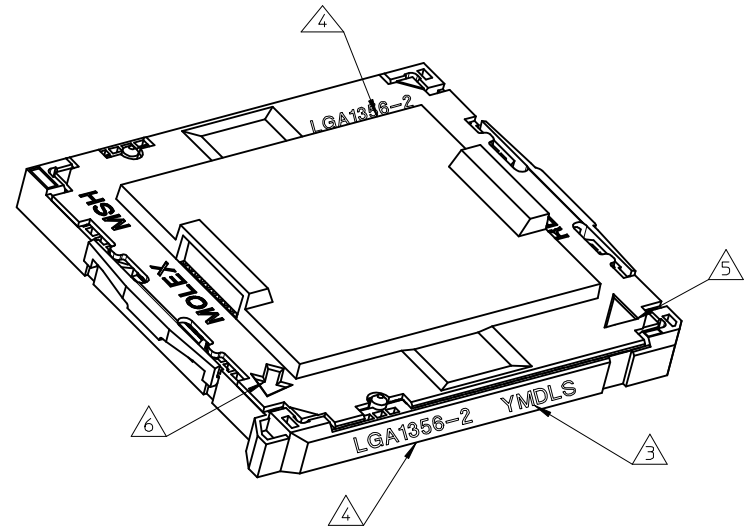
SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

- 3. DATE-CODE LOCATION. AND DATE-CODE *YMDLS* IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)
- 4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

5. SOCKET PIN 1 INDICATOR.

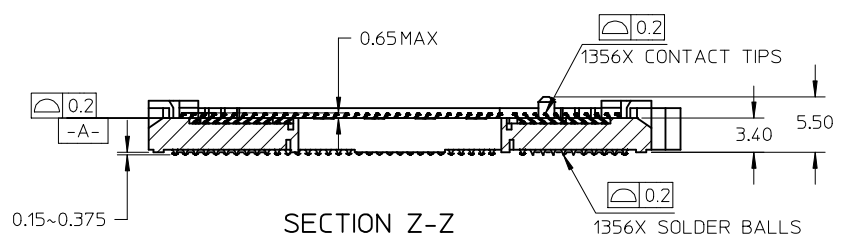
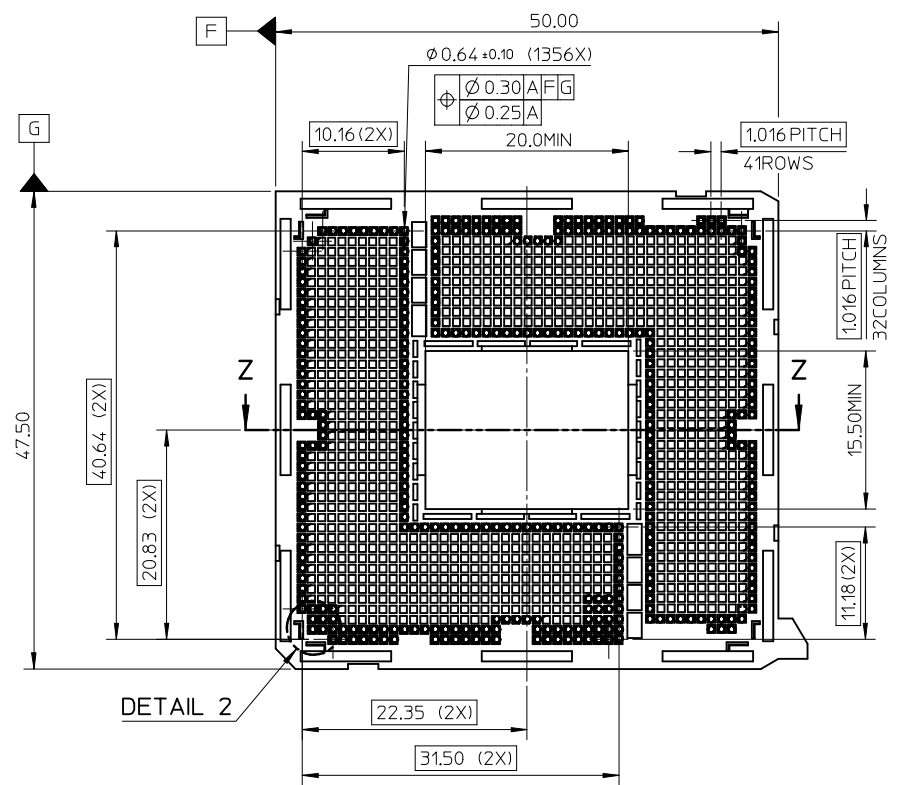
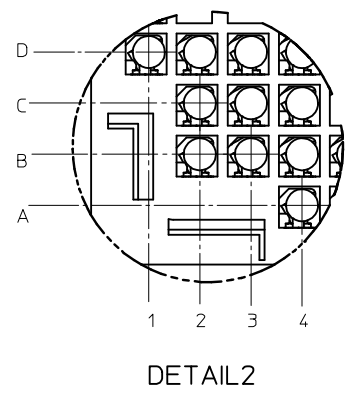
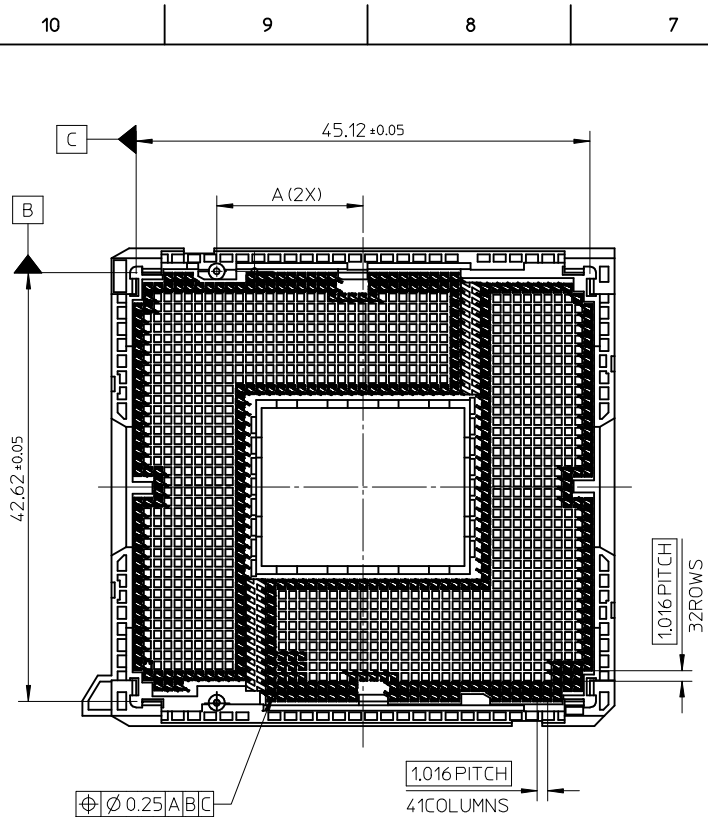
6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

- 7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.
- 8. PRODUCT PACKAGE PK-47594-003 APPLIES.
- 9. THE PARTS 47594*001/*002 COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

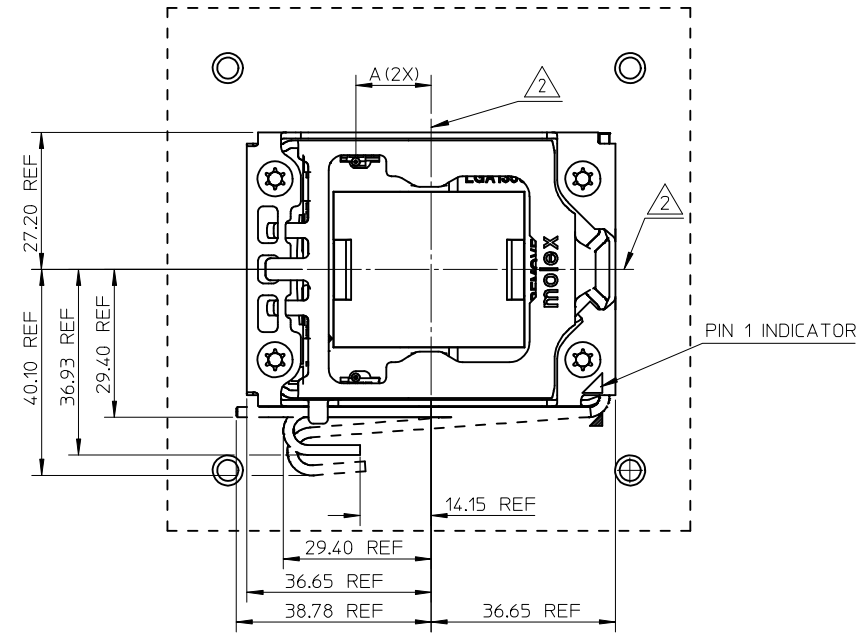
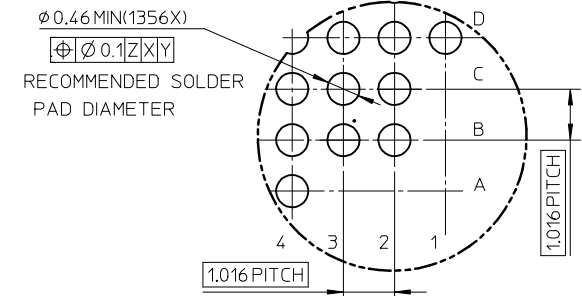
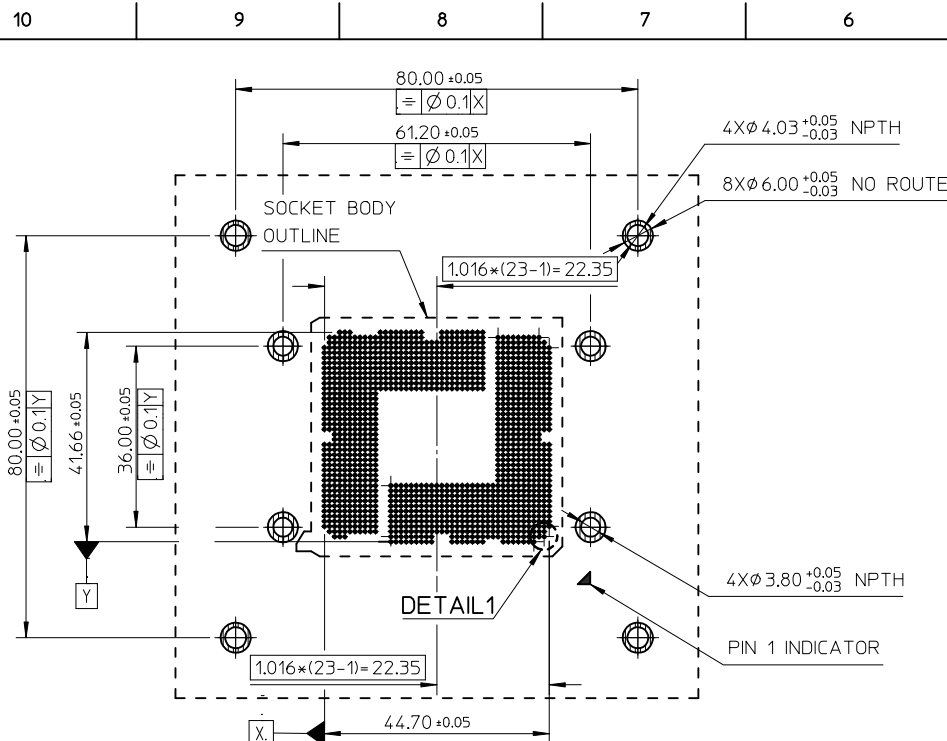


LGA1356 SOCKET PART NUMBER LIST					PART NAME	REMARK
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT		
475943001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-2(B2)	DIM.A=12.85
475943002	GENERAL	30u*(0.76um)				

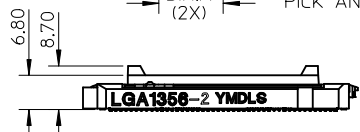
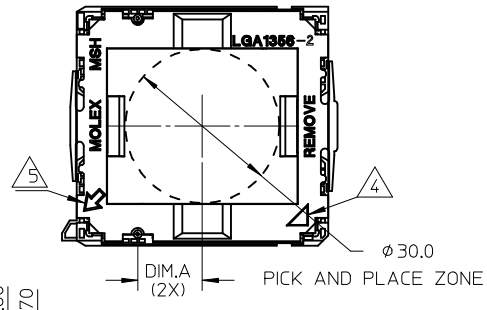
RELEASED EC NO: SH2013-0064 DRWN: YZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	$F_A=0$	mm	INCH	DRAWN BY JZHANG11	DATE 2010/2/10	TITLE LGA1356 SOCKET FULL ASSEMBLY		
	$F_C=0$	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY	DATE	APPROVED BY AYIN		
	$F_B=0$	2 PLACES ± 0.20 ± ---	1 PLACE ± 0.25 ± ---	DATE 2011/07/12		MOLEX INCORPORATED		
	ANGULAR ± 1°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-47594-100	SHEET NO. 1 OF 3	
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS $\nabla_{\text{A}} = 0$ $\nabla_{\text{B}} = 0$ $\nabla_{\text{C}} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± 0.25	± ---	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES	± ---	± ---																		
	3 PLACES	± ---	± ---																		
2 PLACES	± 0.20	± ---																			
1 PLACE	± 0.25	± ---																			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY JZHANG11	DATE 2010/2/10	TITLE LGA1356 SOCKET FULL ASSEMBLY	APPROVED BY AYIN	DATE 2011/07/12	MOLEX INCORPORATED															
MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-47594-100	SHEET NO. 2 OF 3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																		



RECOMMEND PCB LAYOUT THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
 - GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
 - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 - SOCKET PIN 1 INDICATOR.
 - ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
 - ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.

RELEASED IEC NO: SH2013-0064 DRWN: YXZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS $\nabla_F=0$ $\nabla_E=0$ $\nabla_B=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> <tr> <td colspan="3">ANGULAR ± 1°</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± 0.25	± ---	ANGULAR ± 1°			DIMENSION STYLE MM ONLY DRAWN BY: JZHANG11 DATE: 2010/2/10 CHECKED BY:	SCALE 1:1 DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																				
	4 PLACES	± ---	± ---																				
	3 PLACES	± ---	± ---																				
2 PLACES	± 0.20	± ---																					
1 PLACE	± 0.25	± ---																					
ANGULAR ± 1°																							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY: AYIN DATE: 2011/07/12 MATERIAL NO.	TITLE LGA1356 SOCKET FULL ASSEMBLY																				
		SEE TABLE	MOLEX INCORPORATED																				
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	DOCUMENT NO. SD-47594-100		SHEET NO. 3 OF 3																		

NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

3. DATE-CODE LOCATION, AND DATE-CODE "YMDLS"
 IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)

4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

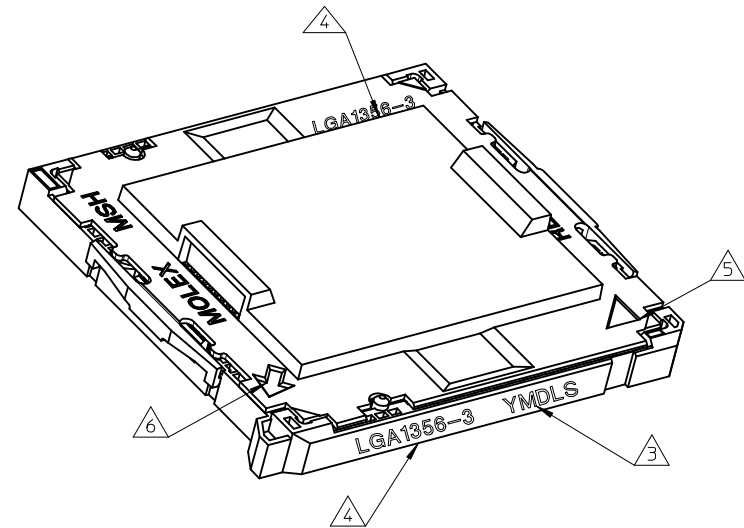
5. SOCKET PIN 1 INDICATOR.

6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

8. PRODUCT PACKAGE PK-47594-003 APPLIES.

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 DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

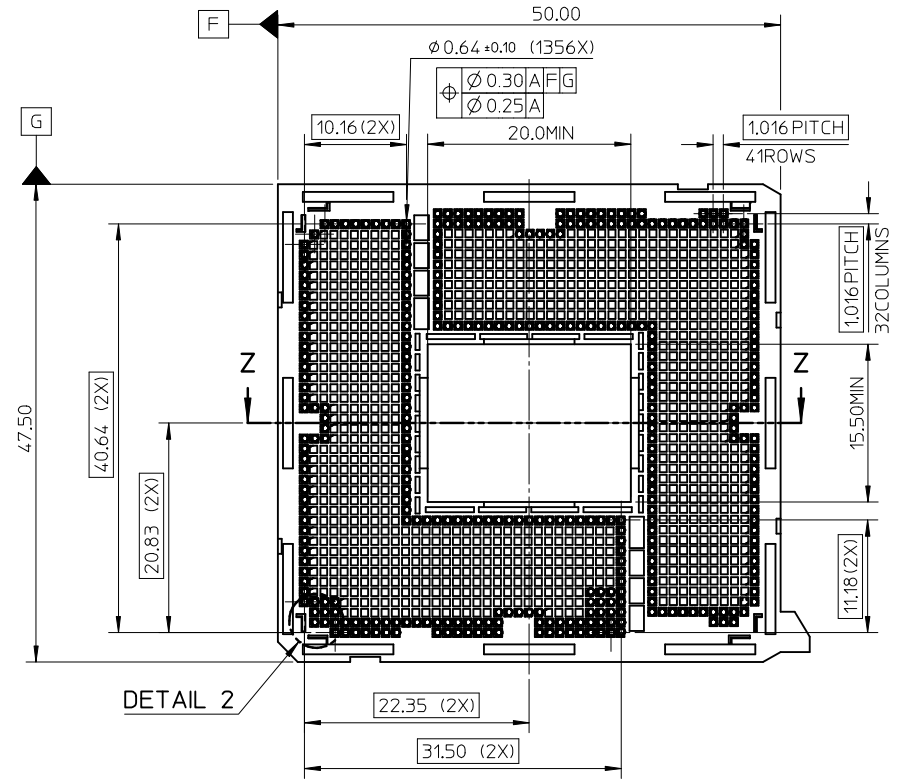
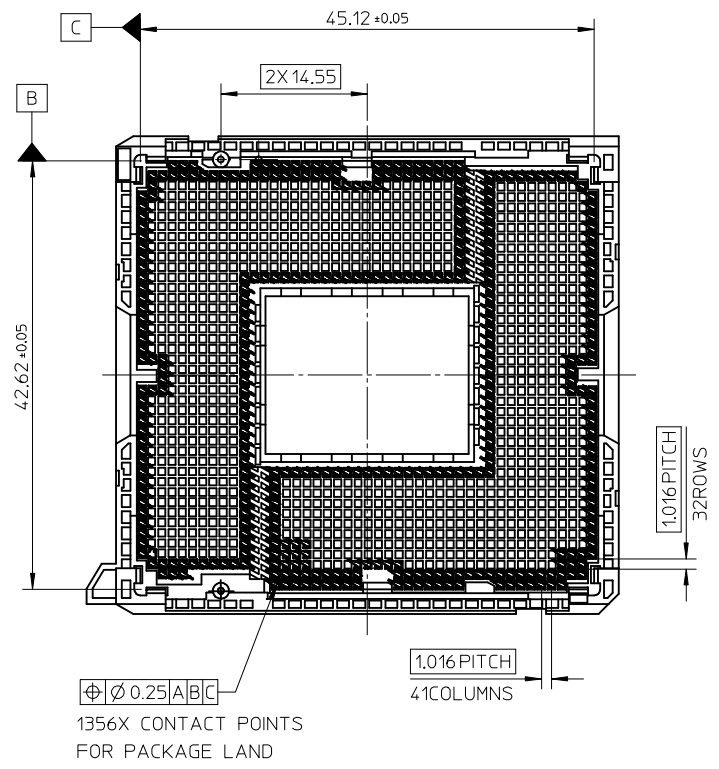


LGA1356 SOCKET PART NUMBER LIST					PART NAME
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT	
475942001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-3(B3)
475942002	GENERAL	30u*(0.76um)			

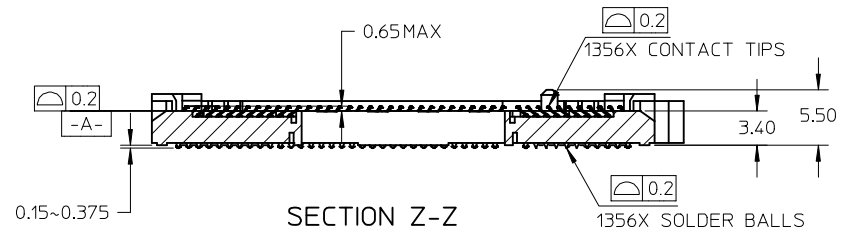
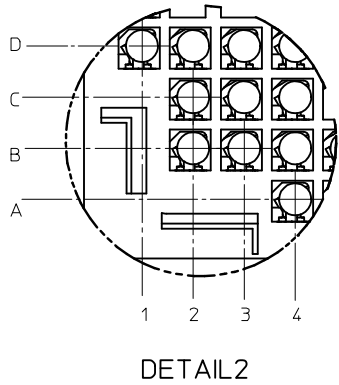
NEW RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/09/24 CH'KD: APPR: AYIN 2013/02/04 REV 1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$F_{\square}=0$	4 PLACES	mm	MM ONLY	2:1	METRIC	LGA1356-3 SOCKET(B3) FULL ASSEMBLY
	$F_{\square}=0$	3 PLACES	INCH	DRAWN BY	DATE	TITLE	
	$F_{\square}=0$	2 PLACES	± 0.20	YXZHENG	2012/09/24	SEE TABLE	
		1 PLACE	± 0.25	CHECKED BY	DATE	APPROVED BY	
	0 PLACE	± 0.25	AYIN	2013/02/04	MATERIAL NO.	DOCUMENT NO.	
		ANGULAR $\pm 1^{\circ}$		SEE TABLE		SD-47594-200	SHEET NO. 1 OF 3
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

F
E
D
C
B
A

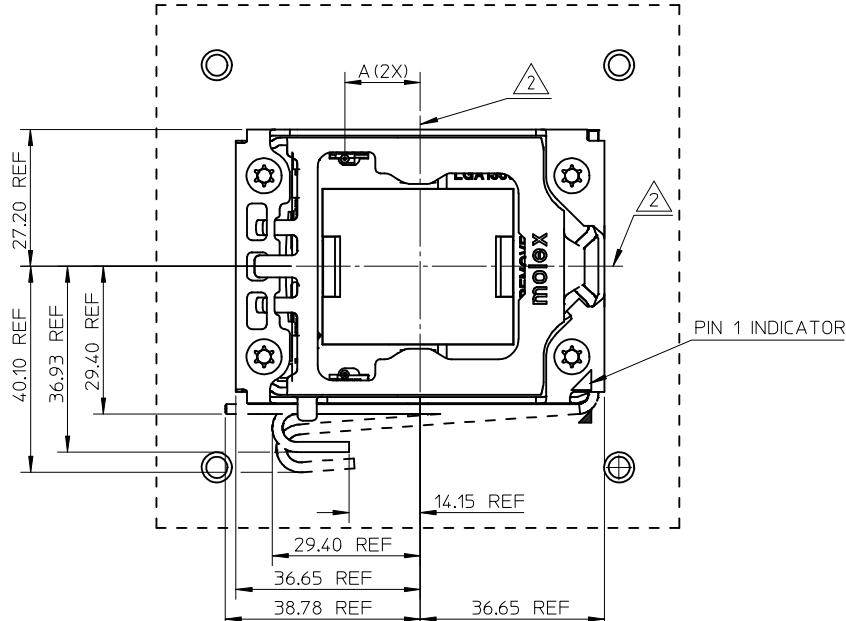
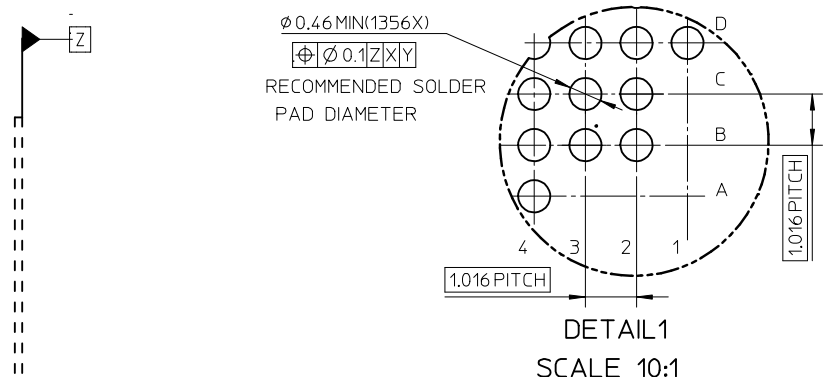
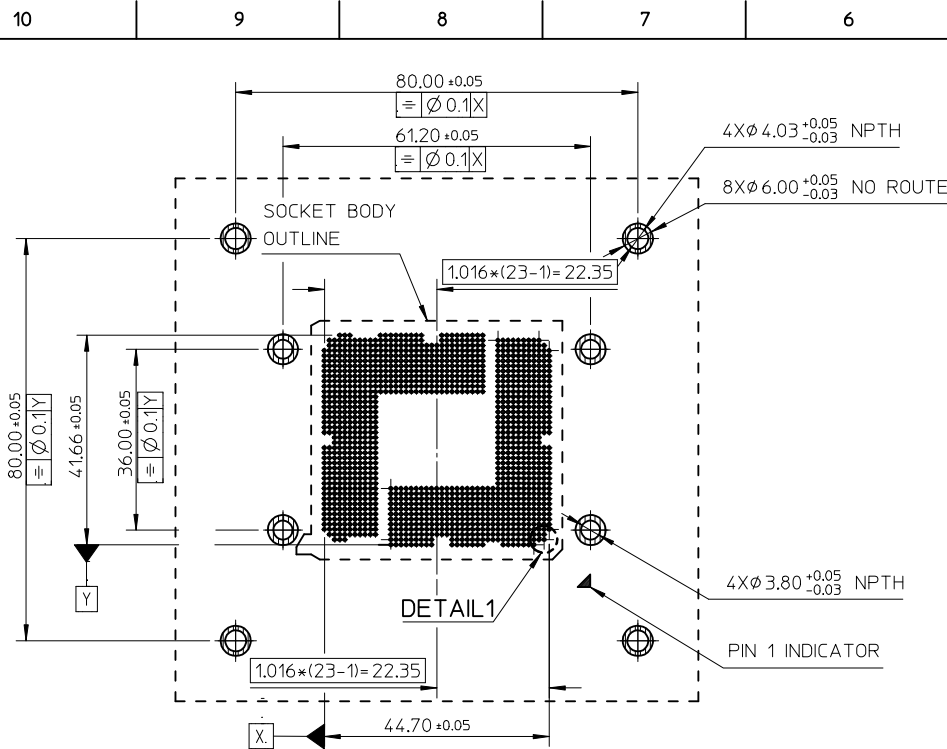


DETAIL 2

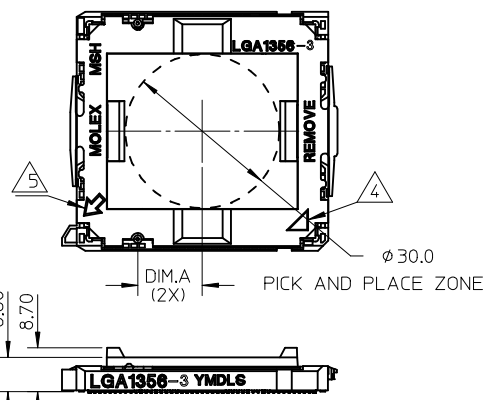


NEW RELEASED EC NO: SHZ013-0064 DRWN: YXZHENG 2012/09/24 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS $F_A=0$ $F_B=0$ $F_C=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± --- ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY DRAWN BY: YXZHENG CHECKED BY: APPROVED BY: AYIN DATE: 2012/09/24 DATE: DATE: 2013/02/04	SCALE 2:1 TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY	DESIGN UNITS METRIC THIRD ANGLE PROJECTION	MATERIAL NO. SEE PAGE 1	DOCUMENT NO. SD-47594-200	SHEET NO. 2 OF 3
	molex							
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
	Rev. G 2012/01/11							

9 8 7 6 5 4 3 2 1



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NEW RELEASED IEC NO: SH2013-0064 DRWN: YXZHENG CHKD: APPR: AYIN 2012/09/24 2013/02/04	QUALITY SYMBOLS $F_{\Delta} = 0$ $F_{\square} = 0$ $F_{\nabla} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	mm INCH ± --- ± --- ± 0.20 ± --- ± 0.25 ± --- ± --- ± ---	DRAWN BY YXZHENG	DATE 2012/09/24	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY AYIN	DATE 2013/02/04	molex			
		ANGULAR ± 1 °		MATERIAL NO. SEE PAGE 1		DOCUMENT NO. SD-47594-200	SHEET NO. 3 OF 3		